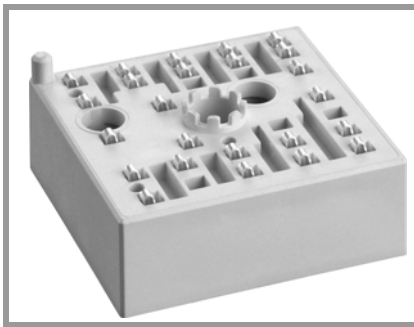
SKiiP 11AC12T4V1



MiniSKiiP® 1

SKiiP 11AC12T4V1

Features*

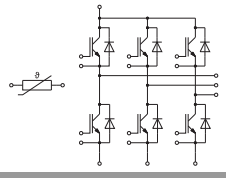
- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

Typical Applications

- Inverter up to 8 kVA
- Typical motor power 4 kW

Remarks

- V_{CEsat} , V_F= chip level value
- Case temp. limited to T_C= 125°C max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. T_{op} = -40 ... +150°C)



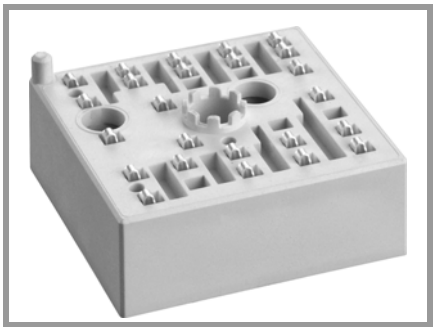
AC

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V_{CES}	T_j = 25 °C		1200	V
I_C	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	12	A
		T_s = 70 °C	12	A
I_C	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	19	A
		T_s = 70 °C	16	A
I_{Cnom}			8	A
I_{CRM}			24	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 800 V $V_{GE} \leq$ 15 V $V_{CES} \leq$ 1200 V	T_j = 150 °C	10	µs
T_j			-40 ... 175	°C
Inverse - Diode				
V_{RRM}	T_j = 25 °C		1200	V
I_F	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	15	A
		T_s = 70 °C	12	A
I_F	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	17	A
		T_s = 70 °C	13	A
I_{FRM}			24	A
I_{FSM}	t_p = 10 ms, sin 180°, T_j = 150 °C		36	A
T_j			-40 ... 175	°C
Module				
$I_{t(RMS)}$	$T_{terminal}$ = 80 °C, 20 A per spring		20	A
T_{stg}	module without TIM		-40 ... 125	°C
V_{isol}	AC sinus 50 Hz, t = 1 min		2500	V

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	I_C = 8 A V_{GE} = 15 V chiplevel	T_j = 25 °C		1.85	2.10	V
		T_j = 150 °C		2.25	2.45	V
V_{CE0}	chiplevel	T_j = 25 °C		0.80	0.90	V
		T_j = 150 °C		0.70	0.80	V
r_{CE}	V_{GE} = 15 V chiplevel	T_j = 25 °C		131	150	mΩ
		T_j = 150 °C		194	206	mΩ
$V_{GE(th)}$	$V_{GE} = V_{CE}$, I_C = 1 mA		5	5.8	6.5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V, T_j = 25 °C				1	mA
C_{ies}	V_{CE} = 25 V V_{GE} = 0 V	f = 1 MHz		0.49		nF
C_{oes}		f = 1 MHz		0.05		nF
C_{res}		f = 1 MHz		0.03		nF
Q_G	V_{GE} = - 8 V...+ 15 V			45		nC
R_{Gint}	T_j = 25 °C			0		Ω
$t_{d(on)}$	V_{CC} = 600 V I_C = 8 A $R_{G\ on}$ = 56 Ω $R_{G\ off}$ = 56 Ω di/dt$_{on}$ = 280 A/µs di/dt$_{off}$ = 90 A/µs	T_j = 150 °C		32		ns
t_r		T_j = 150 °C		28		ns
E_{on}		T_j = 150 °C		0.87		mJ
$t_{d(off)}$		T_j = 150 °C		300		ns
t_f		T_j = 150 °C		65		ns
E_{off}	V_{GE} = +15/-15 V	T_j = 150 °C		0.75		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			1.84		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			1.58		K/W



MiniSKiiP® 1

SKiiP 11AC12T4V1

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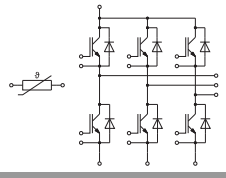
- product rel. results valid for $T_j \leq 150$ (recomm. T_{op} = -40 ... +150°C)

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverse - Diode						
$V_F = V_{EC}$	I_F = 8 A V_{GE} = 0 V chiplevel	T_j = 25 °C		2.33	2.65	V
		T_j = 150 °C		2.35	2.68	V
V_{F0}	chiplevel	T_j = 25 °C		1.30	1.50	V
		T_j = 150 °C		0.90	1.10	V
r_F	chiplevel	T_j = 25 °C		129	144	mΩ
		T_j = 150 °C		181	198	mΩ
I_{RRM}	I_F = 8 A di/dt_{off} = 350 A/µs V_{GE} = +15/-15 V V_{CC} = 600 V	T_j = 150 °C		7.7		A
Q_{rr}		T_j = 150 °C		1.3		µC
E_{rr}		T_j = 150 °C		0.53		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			2.53		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			2.19		K/W
Module						
L_{CE}				-		nH
M_s	to heat sink		2		2.5	Nm
w				30		g
Temperature Sensor						
R_{100}	T_r=100°C (R_{25}=1000Ω)			1670 ± 3%		Ω
$R_{(T)}$	$R_{(T)}$=1000Ω[1+A(T-25°C)+B(T-25°C)^2] , A = 7.635*10^{-3}°C^{-1}, B = 1.731*10^{-5}°C^{-2}					



AC

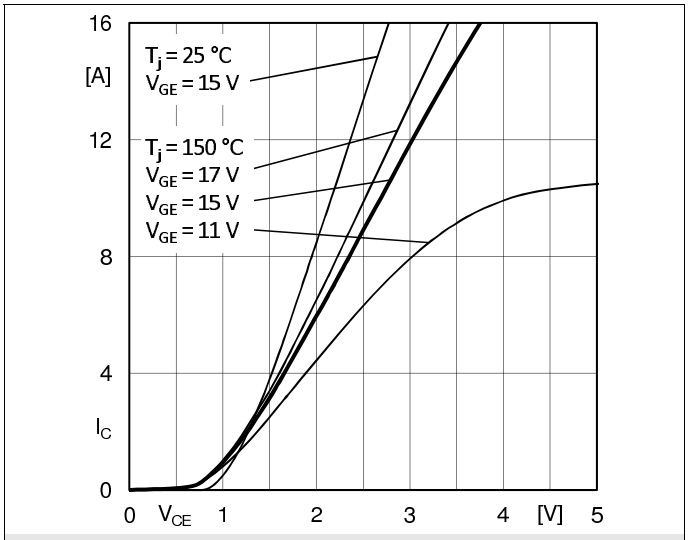


Fig. 1: Typ. output characteristic

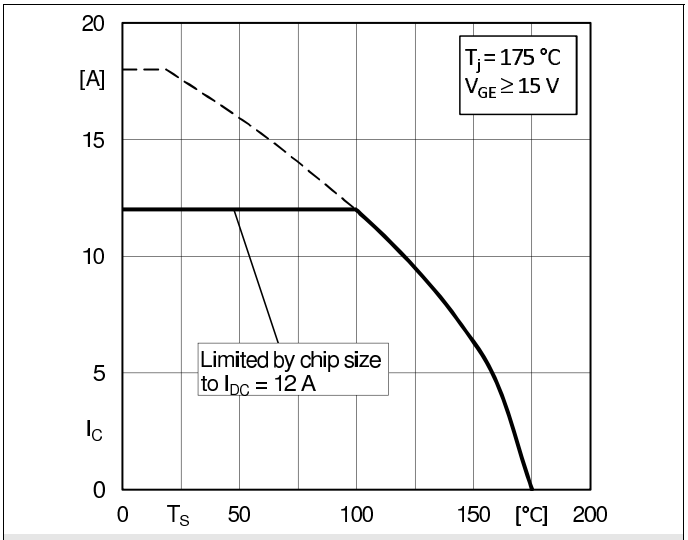


Fig. 2: Rated current vs. temperature $I_C = f(T_S)$

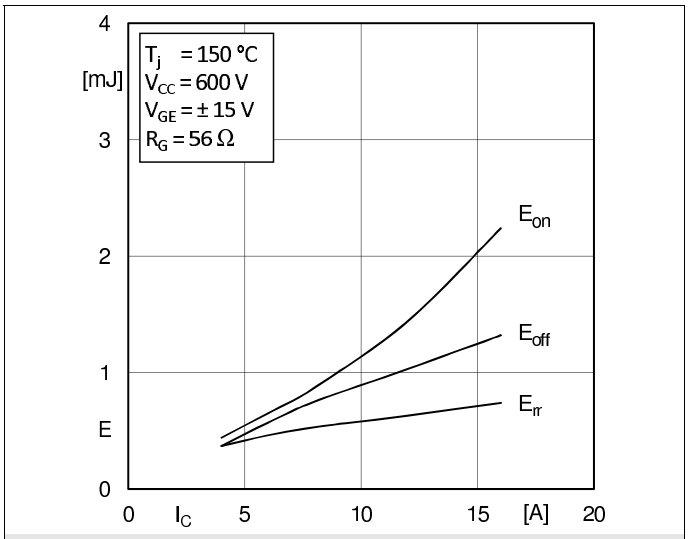


Fig. 3: Typ. turn-on /-off energy = f (I_C)

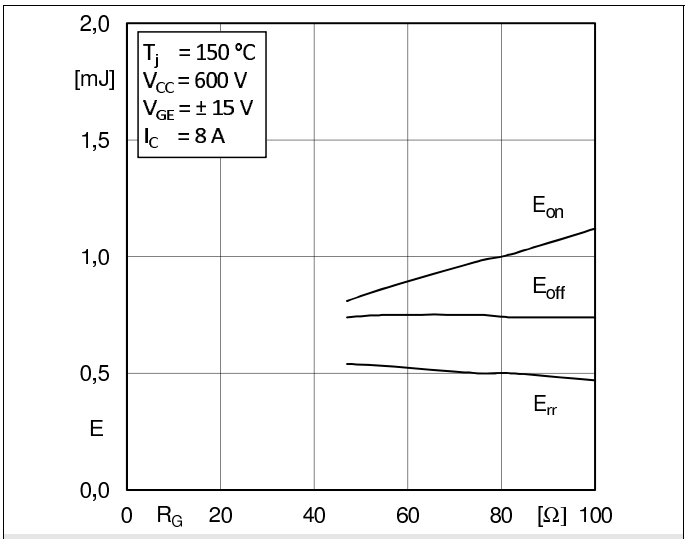


Fig. 4: Typ. turn-on /-off energy = f (R_G)

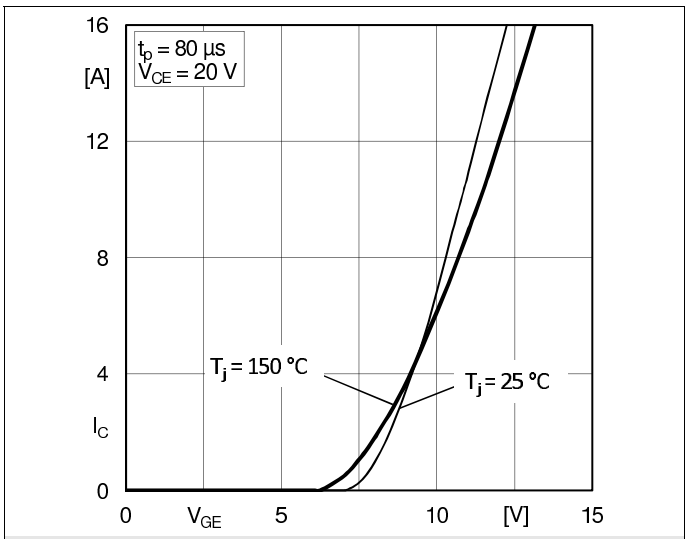


Fig. 5: Typ. transfer characteristic

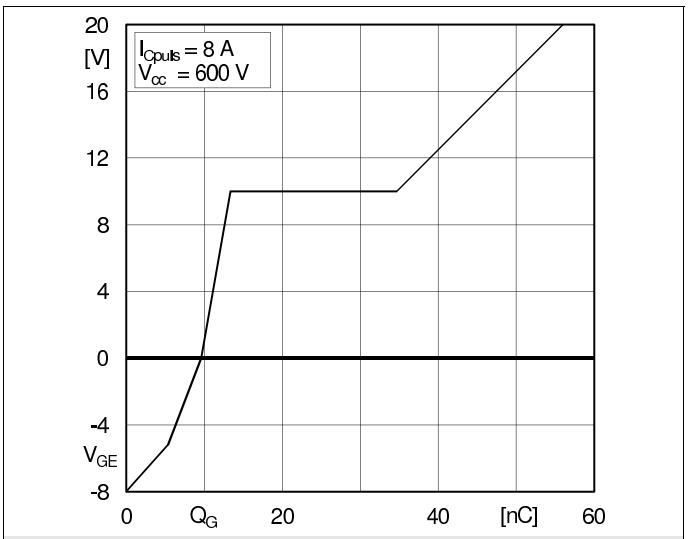


Fig. 6: Typ. gate charge characteristic

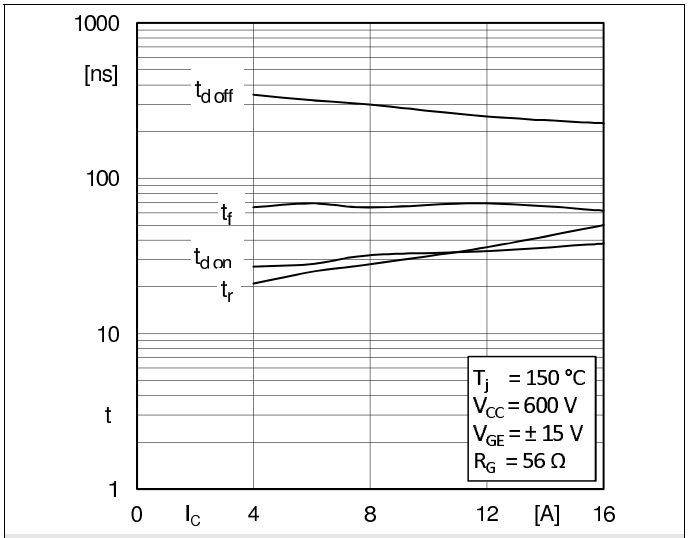


Fig. 7: Typ. switching times vs. I_C

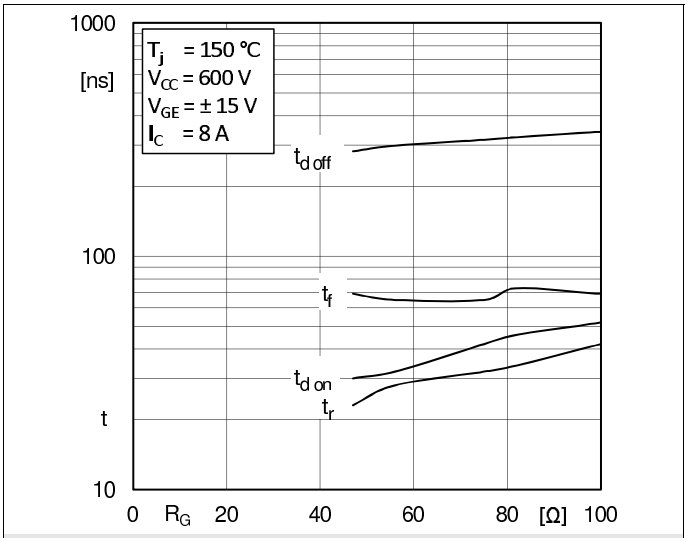


Fig. 8: Typ. switching times vs. gate resistor R_G

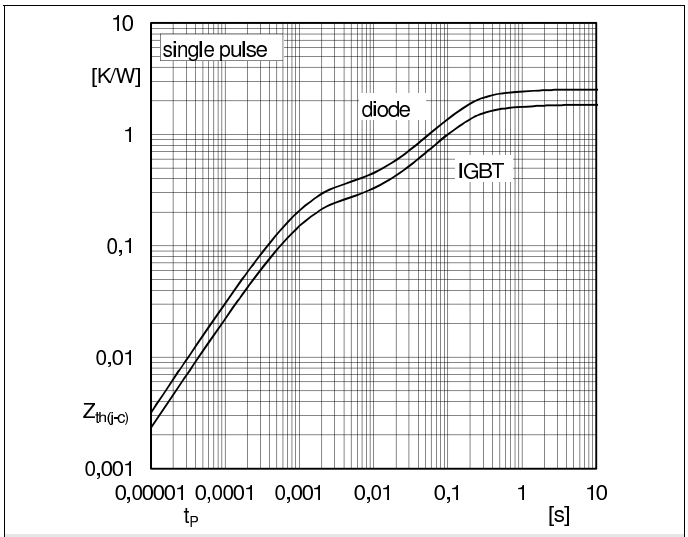


Fig. 9: Typ. transient thermal impedance

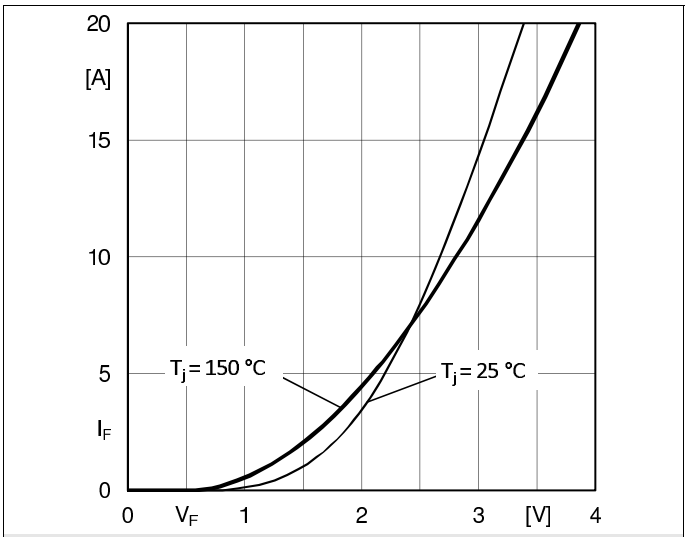


Fig. 10: Typ. CAL diode forward characteristic

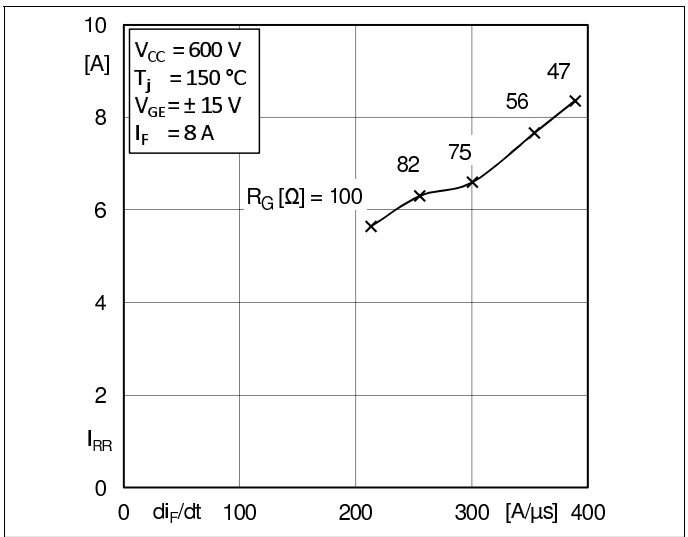


Fig. 11: Typ. CAL diode peak reverse recovery current

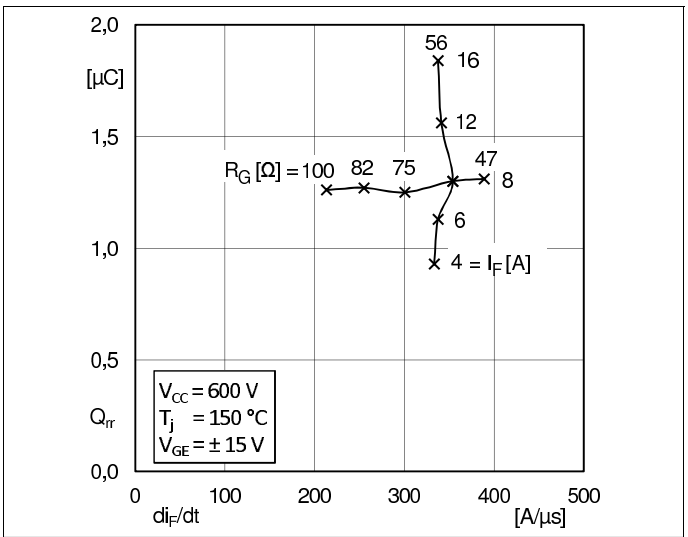
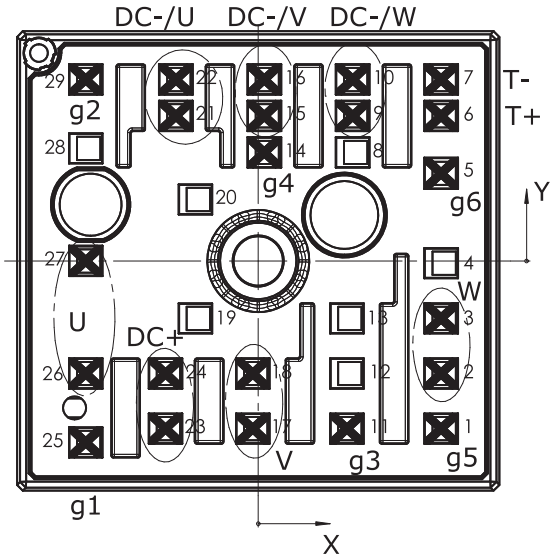


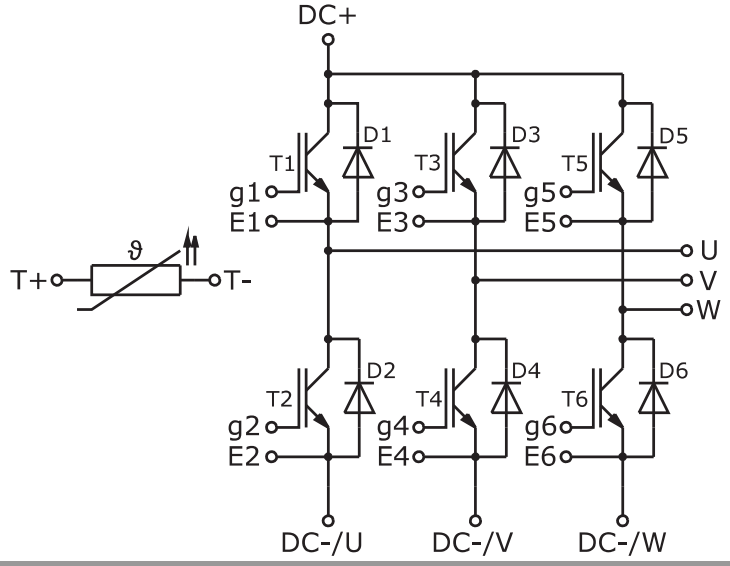
Fig. 12: Typ. CAL diode recovery charge

Pin out							
Pin	*X*	*Y*	*Function*	*Pin*	*X*	*Y*	*Function*
1	15,93	-14,60	g5	16	0,53	15,80	DC-/V
2	15,93	-9,80	W	17	-0,48	-14,6	V
3	15,93	-5,00	W	18	-0,48	-9,80	V
4	15,93	-0,20		19	-5,48	-5,00	
5	15,93	7,63	g6	20	-5,48	5,35	
6	15,93	12,63	T+	21	-7,18	12,63	DC-/U
7	15,93	15,80	T-	22	-7,18	15,80	DC-/U
8	8,23	9,45		23	-8,08	-14,60	DC+
9	8,23	12,63	DC-/W	24	-8,08	-9,80	DC+
10	8,23	15,80	DC-/W	25	-15,03	-15,80	g1
11	7,73	-14,60	g3	26	-15,03	-9,80	U
12	7,73	-9,80		27	-15,03	0	U
13	7,73	-5,00		28	-15,03	9,80	
14	0,53	9,45	g4	29	-15,03	15,80	g2
15	0,53	12,63	DC-/V				

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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